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PATENT APPLICATION

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Applicants: **Nallan et al.**

Case no.: **7017/ETCH/CONE**

Serial No.: **10/092,795**

Filed: **March 6, 2002**

Group Art Unit: **2812**

Examiner: **Not yet assigned**

Title: **METHOD OF PLASMA ETCHING OF HIGH-K DIELECTRIC
MATERIALS WITH HIGH SELECTIVITY TO UNDERLYING
LAYERS**

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Att: Official Draftsman

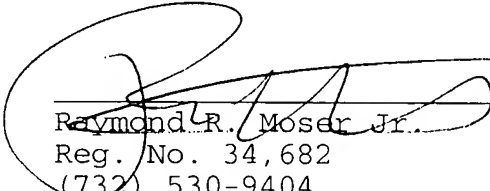
S I R:

SUBMISSION OF FORMAL DRAWINGS

Applicants submits herewith four (4) sheets of formal drawings (FIGs. 1-4) in connection with the above-captioned application.

Respectfully submitted,

5-11-02


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I hereby certify that this correspondence is being deposited on May 14, 2002 with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

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Signature

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